

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.20738	100.0	4.08212
Subtotal				0.20738	100	4.08212
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.19063	7.7	43.12
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.41396	12.0	67.2
	Filler	Silica fused	60676-86-0	22.75976	80.0	448
	Carbon Black	Carbon black	1333-86-4	0.08535	0.3	1.68
Subtotal				28.4497	100	560
Lead Frame	Iron-nickel alloy	Phosphorous (P)	7723-14-0	0.02097	0.03	0.4128
	Iron-nickel alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.75497	1.08	14.8608
	Iron-nickel alloy	Copper (Cu)	7440-50-8	69.05911	98.79	1,359.3504
Subtotal				69.83505	99.9	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.05061	100.0	20.68
Subtotal				1.05061	100	20.68
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01654	10.0	0.32558
	Silver alloy	Silver (Ag)	7440-22-4	0.00331	2.0	0.06512
	Lead alloy	Lead (Pb)	7439-92-1	0.14556	88.0	2.86513
Subtotal				0.16541	100	3.25583
Die		Silicon (Si)	7440-21-3	0.22195	100.0	4.36875
Subtotal				0.22195	100	4.36875
Total				99.9301	100	NaN

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